TS72420K - 10W CW GaN Broadband RF Switch SP4T

1.0 Features

- Low insertion loss: 0.45dB @ 800MHz
- High isolation: 40dB @ 800MHz
- High linear power handling capability
- No external DC blocking capacitors on RF lines
- 40dBm CW hot switching capability
- Versatile 2.6-5.5V power supply
- Operating frequency: 10MHz to 3GHz

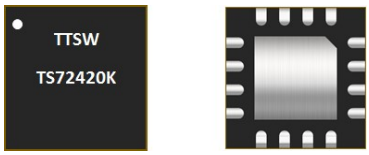


Figure 1 Device Image
(16 Pin 3×3×0.8mm QFN Package)

2.0 Applications

- Private mobile radio handsets
- Public safety handsets
- Cellular infrastructure
- Small cells
- LTE relays and microcells
- Satellite terminals

RoHS/REACH/Halogen Free Compliance

3.0 Description

The TS72420K is a symmetrical reflective Single Pole Four Throws (SP4T) switch designed for broadband, high power switching applications. Its broadband behavior from 10MHz to 3GHz frequencies makes the TS72420K an excellent switch for all applications requiring low insertion loss, high isolation and high linearity within a small package size. This part has the internal charge pump disabled to eliminate the charge pumps spurs. A -17V supply is needed on the Vcp pin.

The TS72420K is packaged into a compact Quad Flat No lead (QFN) 3x3mm 16 leads plastic package.

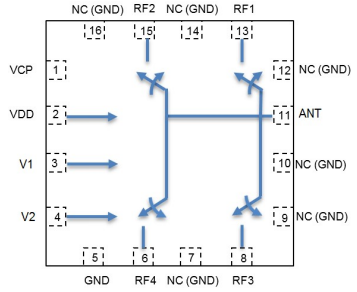


Figure 2 Function Block Diagram
(Top View)

4.0 Ordering Information

Table 1 Ordering Information

Base Part Number	Package Type	Form	Qty	Reel Diameter	Reel Width	Orderable Part Number
TS72420K	16 Pin 3×3×0.8mm QFN	Tape and Reel	3000	13” (330mm)	18mm	TS72420KMTRPBF
Evaluation Board						TS72420K-EVB

5.0 Pin Description

Table 2 Pin Definition

Pin Number	Pin Name	Description
1	VCP	Negative Voltage supply, -17V
2	VDD	DC power supply
3	V1	Switch control input 1
4	V2	Switch control input 2
6	RF4	RF port 4
5,7,9,10,12,14,16	NC	No internal connection, Can be grounded
8	RF3	RF port 3
11	ANT	Antenna port
13	RF1	RF port 1
15	RF2	RF port 2

Note: The backside ground (thermal) pad of the package must be grounded directly to the ground plane of PCB with multiple vias to ensure proper operation and thermal management.

6.0 Absolute Maximum Ratings

Table 3 Absolute Maximum Ratings @T_A=+25°C Unless Otherwise Specified

Parameter	Symbol	Value	Unit
Electrical Ratings			
Power Supply Voltage	VDD	2.6 to 5.5	V
Charge Pump Voltage	VCP	-15 to -18	V
Storage Temperature Range	T_{st}	-55 to +125	°C
Operating Temperature Range	T_{op}	-40 to +85	°C
Maximum Junction Temperature	T_J	+140	°C
RF Input Power CW, 800MHz	RFx	42	dBm
Thermal Ratings			
Thermal Resistance (junction-to-case) – Bottom side	$R_{\theta JC}$	25	°C/W
Thermal Resistance (junction-to-top)	$R_{\theta JT}$	≤ 39	°C/W
Soldering Temperature	T_{SOLD}	260	°C
ESD Ratings			
Human Body Model (HBM)	Level 1B	500 to <1000	V
Charged Device Model (CDM)	Level C3	≥1000	V
Moisture Rating			
Moisture Sensitivity Level	MSL	1	-

Attention:
Maximum ratings are absolute ratings. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding one or a combination of the absolute maximum ratings may cause permanent and irreversible damage to the device and/or to surrounding circuit.

7.0 Electrical Specifications

Table 4 Electrical Specifications @T_A=+25°C Unless Otherwise Specified; VDD=+2.7V, VCP= -17V; 50Ω Source/Load.

Parameter	Condition	Minimum	Typical	Maximum	Unit
Operating Frequency		10		3000	MHz
Insertion Loss, RFx	400MHz		0.35		
	800MHz		0.45	0.60	
	1.95GHz		0.60	0.75	
	2.6GHz		0.70	0.85	
Isolation ANT-RFx	400MHz		43		
	800MHz	36	40		
	1.95GHz	28	30		
	2.6GHz	25	27		
Return Loss ANT-RFx	400MHz		25		
	800MHz		23		
	1.95GHz		16		
	2.6GHz		14		
H2	800MHz, Pin=35dBm		-42		dBm
H3	800MHz, Pin=35dBm		-45		dBm
IIP3	800MHz		70		dBm
P0.1dB[1]	0.1dB compression point, 800MHz	40	42		dBm
Switching Time	50% ctrl to 10/90% of the RF value is settled. C1=1nF (refer to Figure 3)		0.65		μs
Control Voltage	Power supply VDD	2.6	3.3	5.5	V
	Charge Pump Supply Voltage	-18	-17	-15	V
	All control pins high, V_{ih}	1.0	3.3	5.25	V
	All control pins low, V_{il}	-0.3		0.5	V
Control Current	All control pins low, I_{il}		0		μA
	All control pins high, I_{ih}			7.5	μA
Current Consumption, IDD	Active mode		160	200	μA

Note:

[1] P0.1dB is a figure of merit.

[2] No external DC blocking capacitors required on RF pins unless DC voltage is applied on a RF pin.

8.0 Switch Truth Table

Table 5 Switch Truth Table

V1	V2	Active RF Path
0	0	ANT-RF1
1	0	ANT-RF2
0	1	ANT-RF3
1	1	ANT-RF4

Bias Sequence:
[1] **VDD should be applied first before VCP**. Min time between VDD and VCP should be 50usec.
[2] Vc can be toggled/switched after VCP has settled.

9.0 Evaluation Board

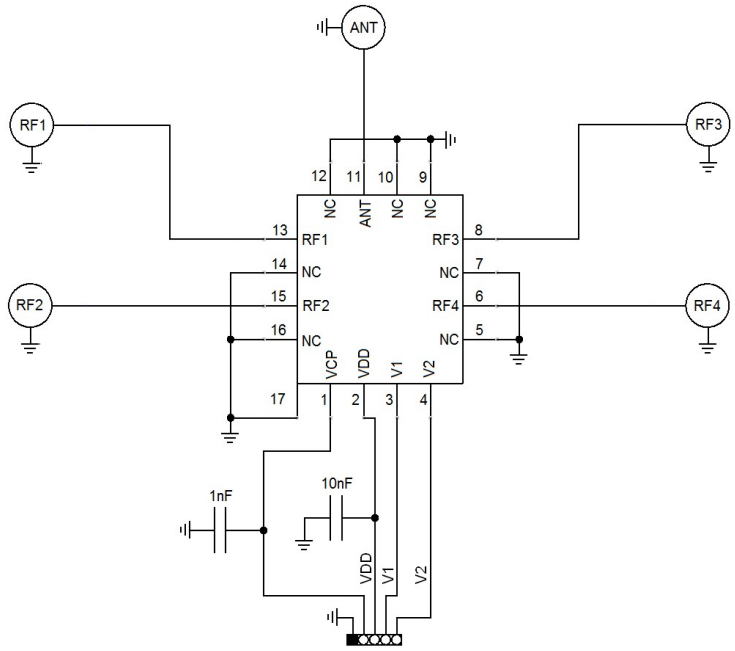


Figure 3 Evaluation Board Schematic

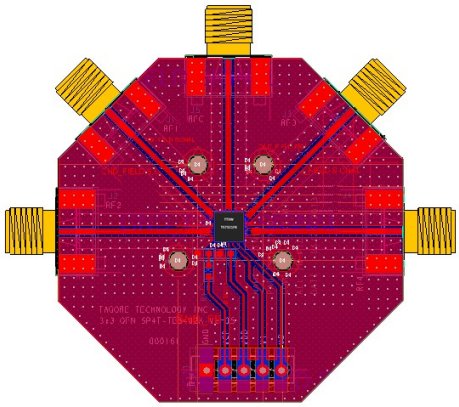


Figure 4 Evaluation Board Image

Attention:
[1] 17 refers to the center pad of the device.
[2] -17V needed on VCP pin.

10.0 Typical Characteristics

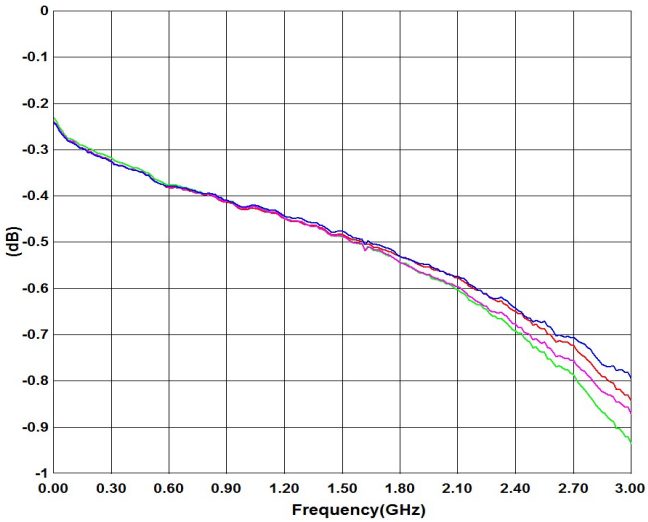


Figure 5 RF1 to RF4 Insertion Loss

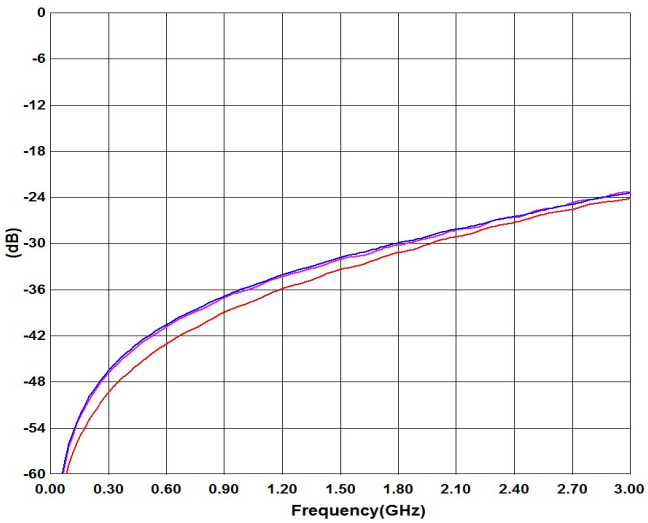


Figure 6 RF1 ON, RF1 Isolation to RF2 to RF4

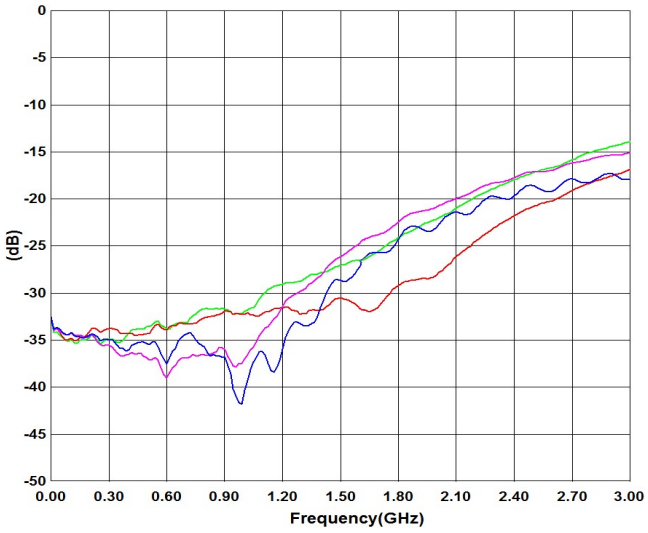


Figure 7 RF1 to RF4 Return Loss

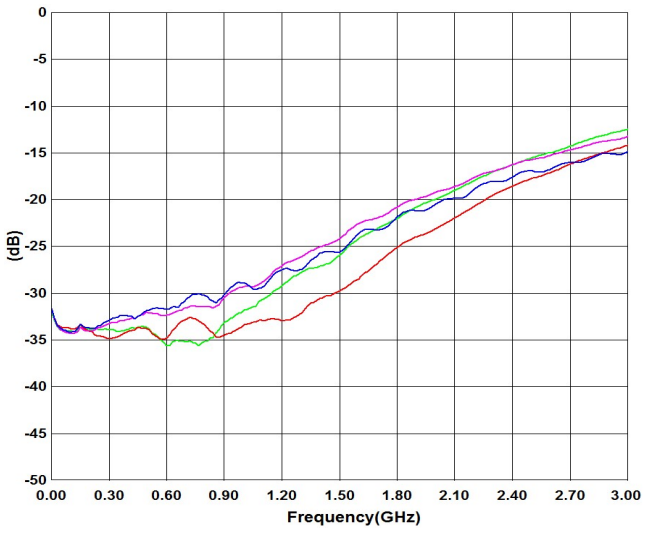


Figure 8 ANT Return Loss

11.0 Device Package Information

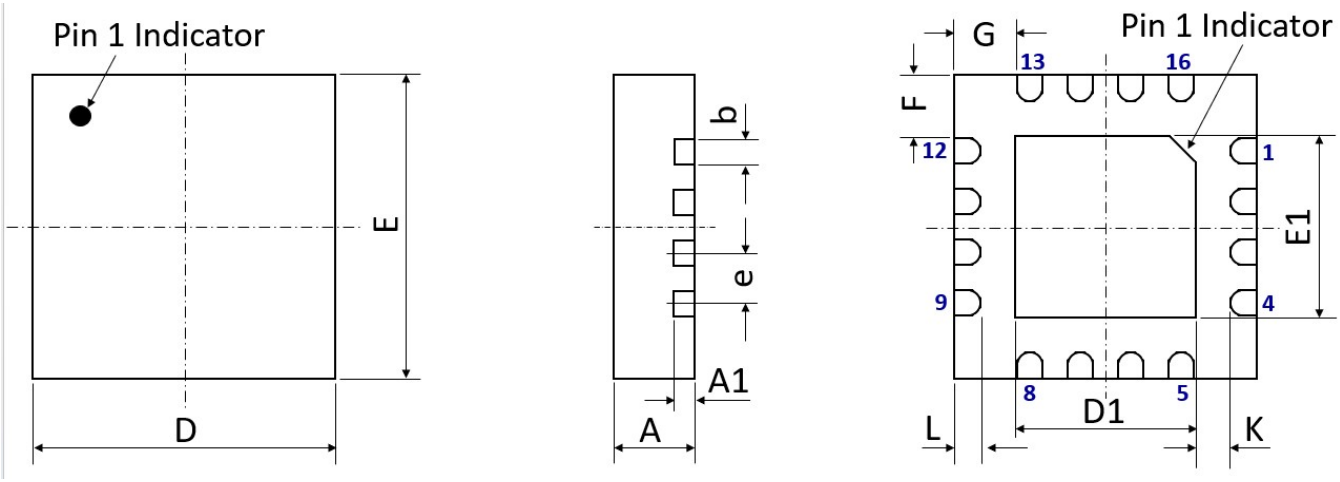


Figure 9 Device Package Drawing
(All dimensions are in mm)

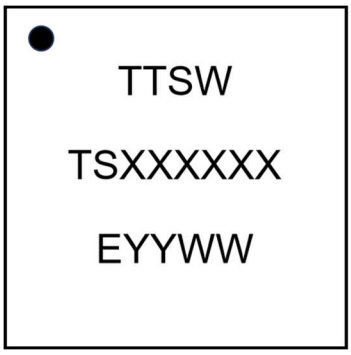
Table 6 Device Package Dimensions

Dimension (mm)	**Value** (mm)	**Tolerance** (mm)	**Dimension** (mm)	**Value** (mm)	**Tolerance** (mm)
A	0.80	±0.05	E	3.00 BSC	±0.05
A1	0.203	±0.02	E1	1.70	±0.05
b	0.25	+0.05/-0.07	F	0.625	±0.05
D	3.00 BSC	±0.05	G	0.625	±0.05
D1	1.70	±0.05	L	0.25	±0.05
e	0.50 BSC	±0.05	K	0.40	±0.05

Note: Lead finish: Pure Sn without underlayer; Thickness: 7.5μm ~ 20μm (Typical 10μm ~ 12μm)

Attention:
Please refer to application notes *TN-001* and *TN-002* at http://www.tagoretech.com for PCB and soldering related guidelines.

Top-marking specification:



● = Pin 1 indicator
TTSW = Tagore Technology SWitch
TSXXXXXX = Part number (8 digits max)
E = A fixed letter before the date code
YY = Last two digits of assembly year
WW = Assembly work week

12.0 PCB Land Design

Guidelines:
[1] 4 layer PCB is recommended.
[2] Via diameter is recommended to be 0.2mm to prevent solder wicking inside the vias.
[3] Thermal vias shall only be placed on the center pad.
[4] The maximum via number for the center pad is 3(X)×3(Y)=9.

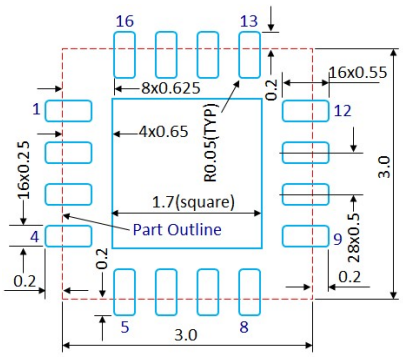
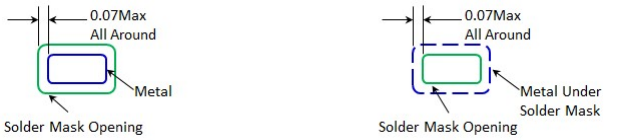


Figure 10 PCB Land Pattern
(Dimensions are in mm)



Non-Solder Mask Defined (Preferred)

Solder Mask Defined

Figure 11 Solder Mask Pattern
(Dimensions are in mm)

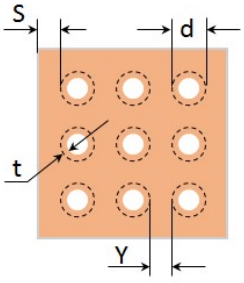


Figure 12 Thermal Via Pattern
(Recommended Values: S≥0.15mm; Y≥0.20mm; d=0.2mm; Plating Thickness t=25μm or 50μm)

13.0 PCB Stencil Design

Guidelines:

[1] Laser-cut, stainless steel stencil is recommended with electro-polished trapezoidal walls to improve the paste release.

[2] Stencil thickness is recommended to be 125µm.

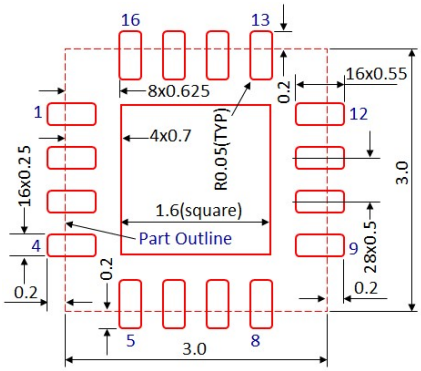


Figure 13 Stencil Openings
(Dimensions are in mm)

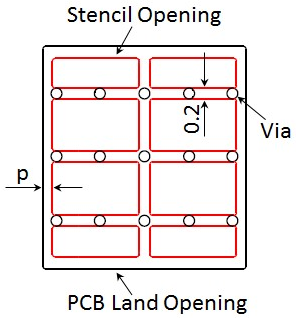


Figure 14 Stencil Openings Shall not Cover Via Areas If Possible
(Dimensions are in mm)

14.0 Tape and Reel Information

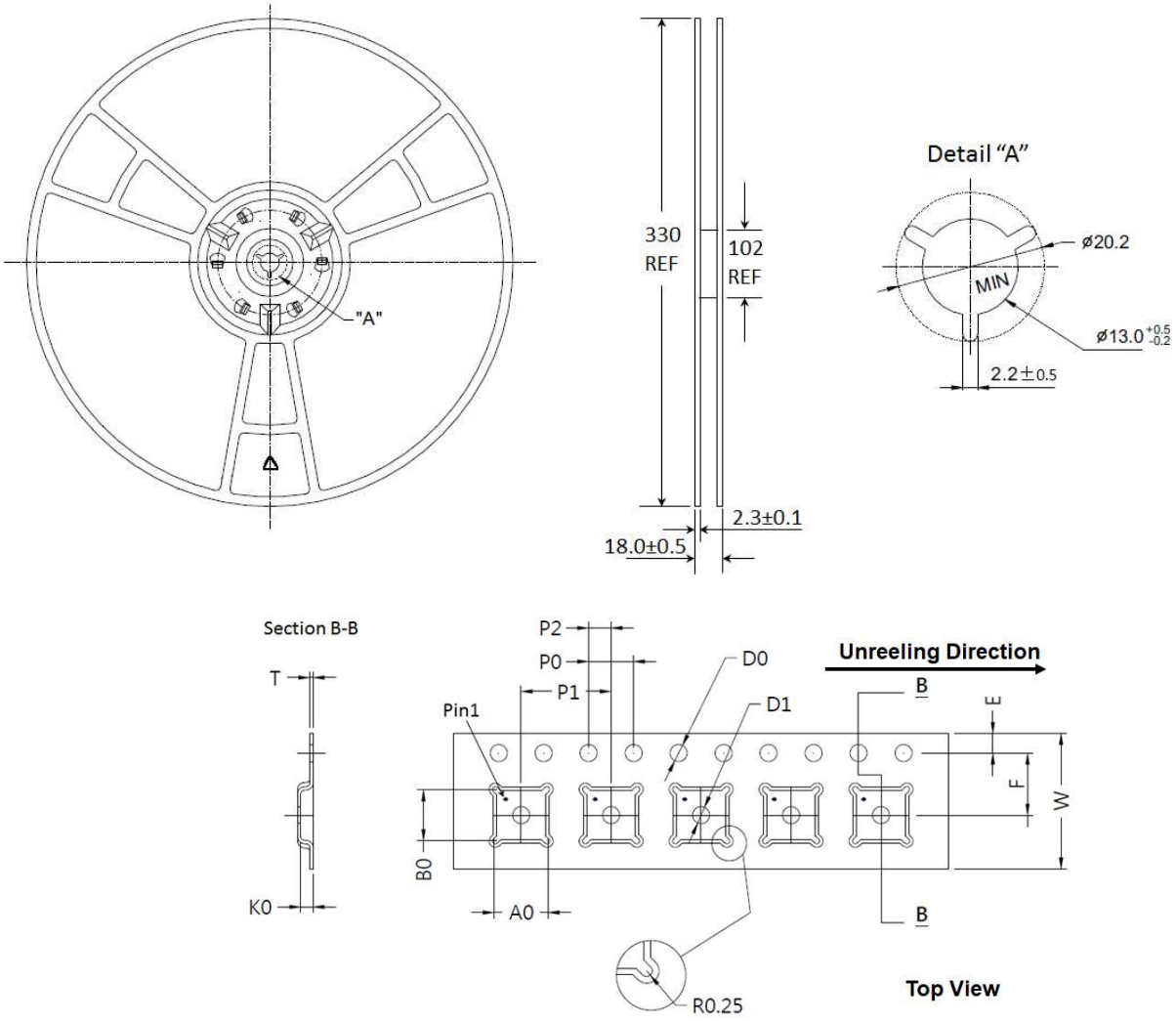


Figure 15 Tape and Reel Drawing

Table 7 Tape and Reel Dimensions

Dimension (mm)	**Value** (mm)	**Tolerance** (mm)	**Dimension** (mm)	**Value** (mm)	**Tolerance** (mm)
A0	3.35	±0.10	K0	1.10	±0.10
B0	3.35	±0.10	P0	4.00	±0.10
D0	1.50	+0.10/-0.00	P1	8.00	±0.10
D1	1.50	+0.10/-0.00	P2	2.00	±0.05
E	1.75	±0.10	T	0.30	±0.05
F	5.50	±0.05	W	12.00	±0.30

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